

Chip Scale Review

2017 Editorial Calendar

(Editorial close date: 11/20)

January • February

* indicates show distribution

Industry forecast	<ul style="list-style-type: none"> • SEMI European 3D Summit Grenoble, France (Jan 23-25) • SMTA Pan Pac Microelectronics Symposium * Kauai, Hawaii (Feb 6-9) • SEMICON Korea Seoul, Korea (Feb 8-10) • APEX Expo San Diego, CA (Feb 14-16) • BiTS Workshop* Mesa, AZ (March 5-8) • IMAPS DPC* Fountain Hills, AZ (March 6-9) • SEMICON China* Shanghai, China (March 14-16)*
Semiconductor merger & consolidation	
Electronic assembly reliability	
Photonics packaging	
Fan-out	
Plasma dicing	
Direct bond technology	
Testing of MEMS / sensors in HVM	
Test & burn-in challenges	

Ad Space Close Jan 6 - Ad Materials Close Jan 11

(Editorial close date: 1/6)

March • April

* indicates show distribution

Metrology for advanced packaging applications	<ul style="list-style-type: none"> • SEMICON SE Asia Penang, Malaysia (Apr 25-27) • ECTC * Lake Buena Vista, FL(May 30- June 2)
3D integration technology for high-density, high performance ICs	
Chip package interaction	
Automotive electronic challenges	
Die attach	
Electronic materials	
3D technology failure analysis	
Hi density FO package for RF applications	
Advances in FOWLP	

Ad Space Close Feb 10 - Materials Close Feb 15

(Editorial close date: 3/10)

May • June

* indicates show distribution

Thin wafer handling	<ul style="list-style-type: none"> • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 5-8) • Sensors Expo San Jose, CA (June 27-29) • SEMICON West * San Francisco, CA (July 12-14)
Wafer probing	
Wafer test	
Adhesives, underfill, encapsulants	
Semiconductor mergers	
Lithography solutions for MEMS	
System in package (SiP)	
Advances in thermal management	
Feature: 50 years of CEA-Leti – past, present, future	

Ad Space Close May 19 - Ad Materials Close May 24